

# Forward-looking Statements

## Safe Harbor | Disclaimers

This presentation contains forward-looking statements within the meaning of federal securities laws, including statements regarding expectations for: our business outlook, financial condition and financial and operational performance; demand trends, market conditions and market opportunities; our capital expenditures and capital allocation priorities; and the availability and performance of our future products and technologies. These forward-looking statements are based on management's current expectations and are subject to risks and uncertainties that could cause actual results to differ materially from those expressed or implied in the forward-looking statements.

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 Western Digital.

# Investor Day

May 10, 2022 \ San Francisco, CA



What's Next  
**Western  
Digital.**

# Technology Strategy and Roadmaps

**Siva Sivaram**

President of Technology & Strategy  
Western Digital



What's Next  
**Western  
Digital.**

# 01

## Technology and Development Strategy

# Technology Development Strategy



Lead

**Areal Density**



Leverage High Performance

**Charge Trap Cell**



Reimagine Every  
Subsystem

**HDD**



Drive Capital Efficient  
Bit Growth

**Flash**

# A Well Directed Research Engine



**In-Depth Know-How  
in Magnetics and  
Solid-State Memories**

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**~14K Active Patents**



**Unique Technology  
Solutions Arising from  
Targeted Development  
Strategies**

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**OptiNAND**

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**UltraSMR and ZNS (Zone Named Spaces)**

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**Revolutionary New Products**

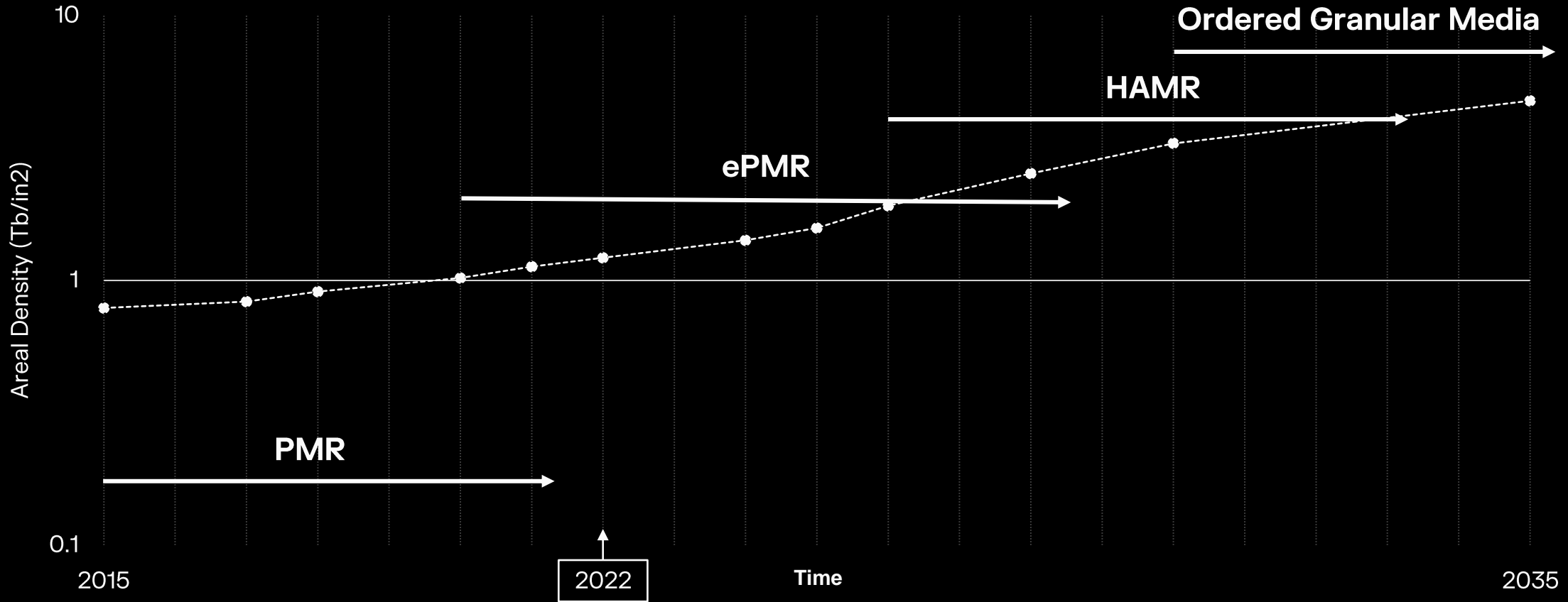
# 02

## HDD Technology Direction



What's Next  
**Western  
Digital**

# Areal Density Leadership



**ePMR Provides Multi-Generational Leadership**

# HDD is Innovating for the Cloud

Storage  
Density

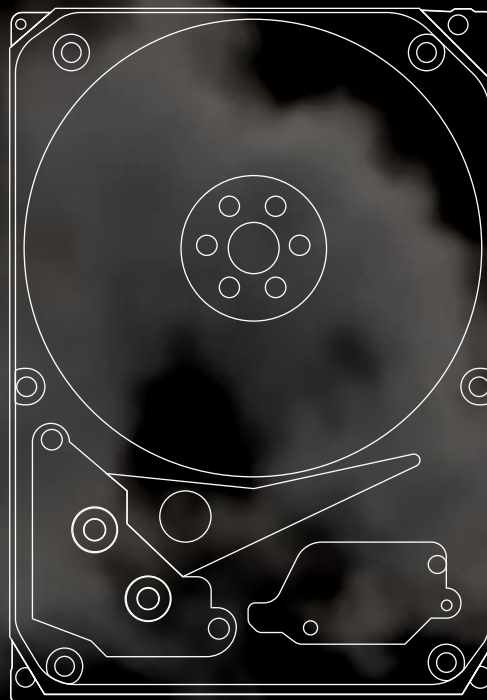
Access  
Time

Reliability

Total Cost  
of Ownership

Capacity

Sustainability

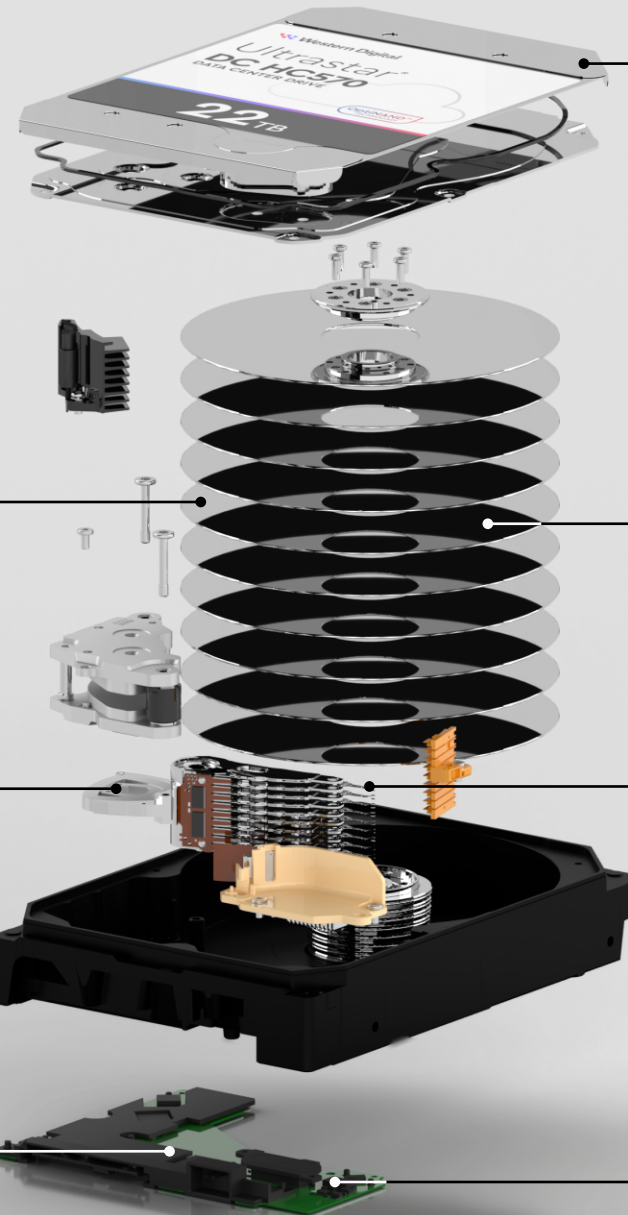


Proximity  
to the Edge

Performance



# Reimagining the HDD



Helium Seal

Recording Format  
CMR | SMR | UltraSMR

Magnetic Media  
Ultra-Thin AlMg Substrates

Micro-Positioning  
Single Stage | Dual Stage | Triple Stage Actuation

Recording Heads  
PMR | ePMR

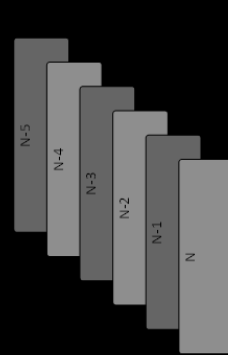
Access Density  
1 Head Active at a Time | 2 Heads Active

SOC and Flash  
DRAM Only | OptiNAND

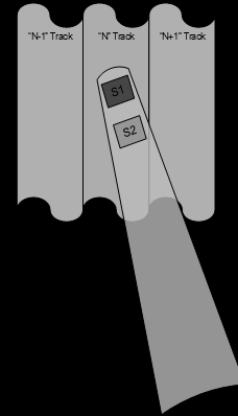
# UltraSMR



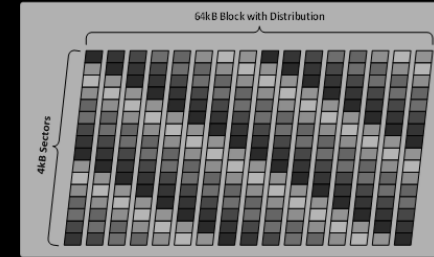
=



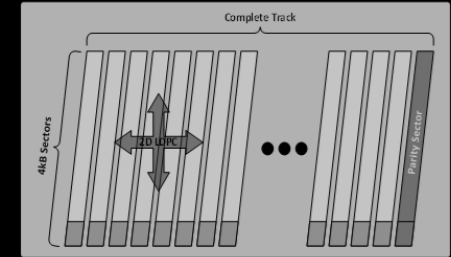
SMR System



TDMR



Distributed Sector



Soft Track ECC

## Enabled by OptiNAND

# The Only Shipping 22TB Drive



Shipping

**22TB**

Drives to Select Customers



Sampling

**26TB**

UltraSMR Drives



What's Next  
**Western  
Digital.**

# 03

# Flash Technology

# Flash Ventures

## A Unique Partnership Model

**23**  
YEARS

Deep, Longstanding  
**23-Year Partnership**

**15**  
NODES

Introduced **15 Generations**  
of Leading-Edge Technology  
Nodes

**#1**

**Yokkaichi Mega Fab**  
Complex is the World's  
Largest NAND  
Manufacturing Site

 **Western Digital**

+

**KIOXIA**

**BiCS5 Bit Crossover in FQ2'22**

**BiCS6 Volume Ramp in  
FQ2'23**

**Y7 Fab Production Starts  
in FQ1'23**

**BiCS+ Preview Today**

# Joint Venture Operational Framework

 Western Digital

**KIOXIA**

**Flash Ventures**  
49.9% Owned by Western Digital  
50.1% Owned by Kioxia

Flash Forward, Ltd.  
(2010 – 2034)

Flash Alliance, Ltd.  
(2006 – 2029)

Flash Partners, Ltd.  
(2004 – 2029)

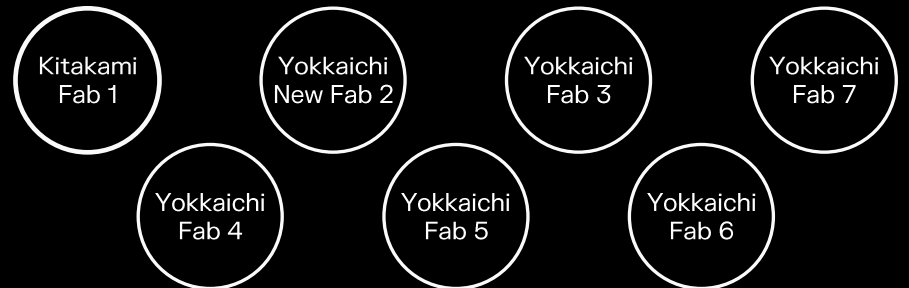
Non-JV  
Output  
**20%**

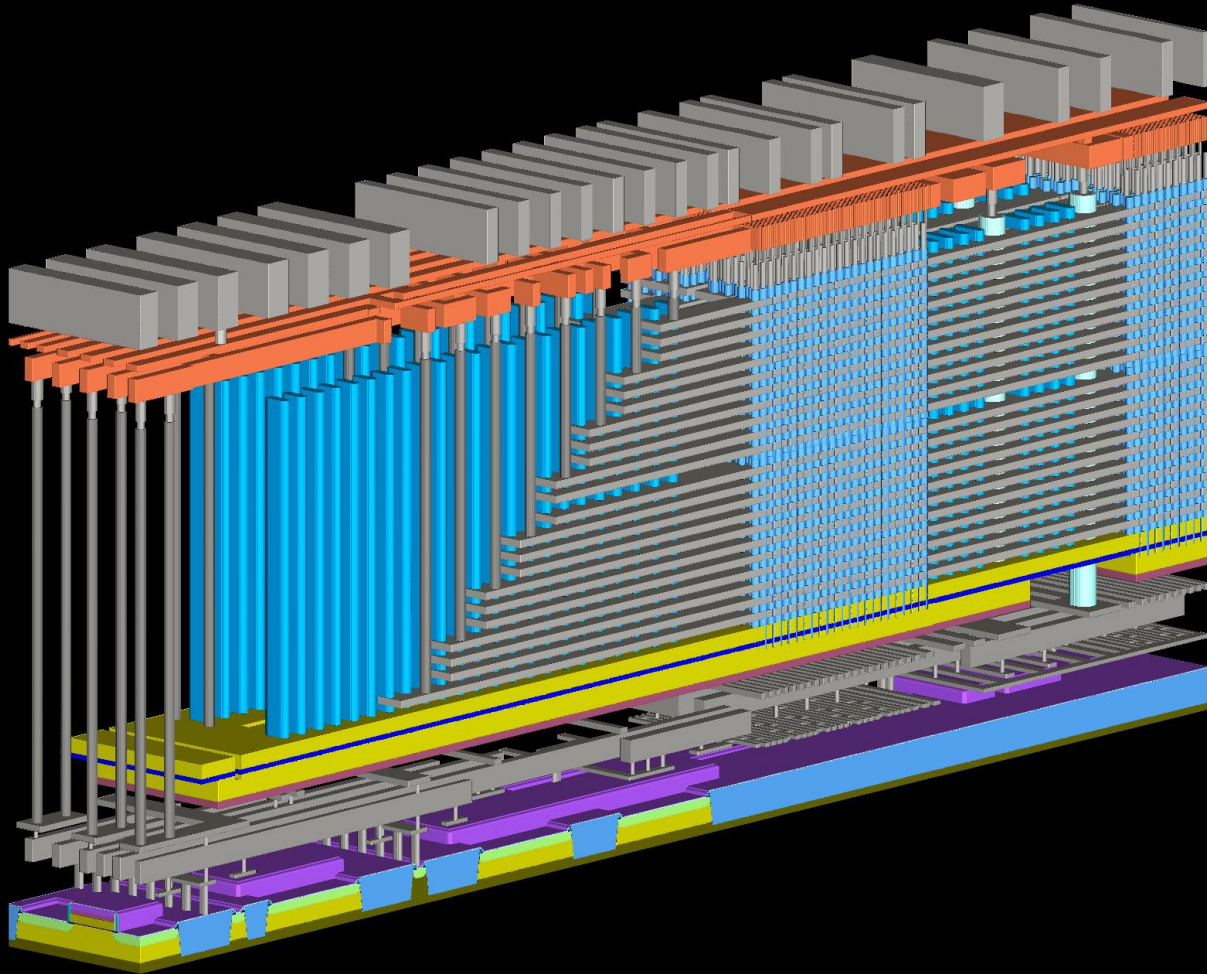
## Joint Memory Development

- Memory Development Center integrated within Yokkaichi mega fab complex enabling quicker ramp to production
- Shared NAND Flash Designs

80%

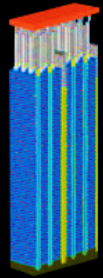
## Fabs





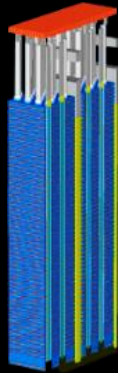
# 20 Years of NAND Innovation

# NAND Technology Staging



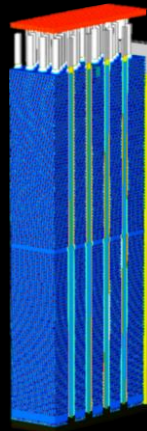
**48-Layer  
(BiCS2)**

2016



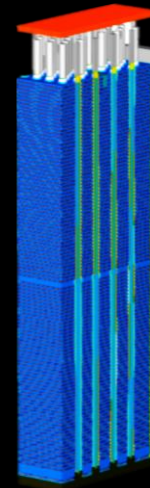
**64-Layer  
(BiCS3)**

2017



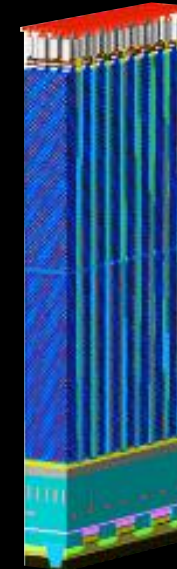
**96-Layer  
(BiCS4)**

2019



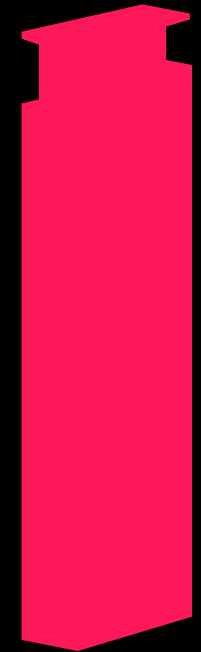
**112-Layer  
(BiCS5)**

2020



**162-Layer  
(BiCS6)**

2022

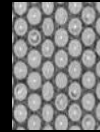


**2xx-Layer  
(BiCS+)**

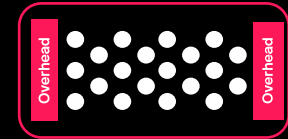


# NAND Technology Staging

## Lateral Scaling

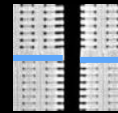


Memory Hole Density

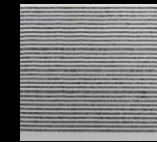


Staggering & Overhead Reduction

## Vertical Scaling

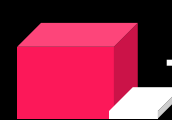


Multi-Tiered Memory Hole

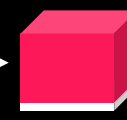


Thin & Low Resistive Memory Layers

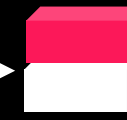
## Architecture Scaling



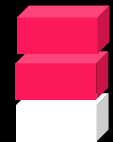
CNA



CUA

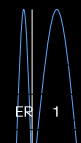


CBA

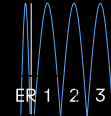


Multi-Bonding

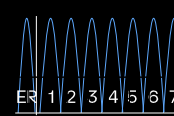
## Logical Scaling



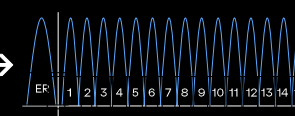
SLC



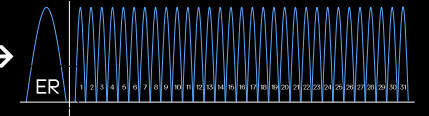
MLC



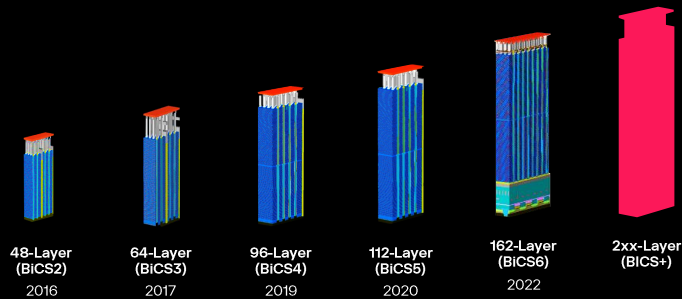
TLC



QLC

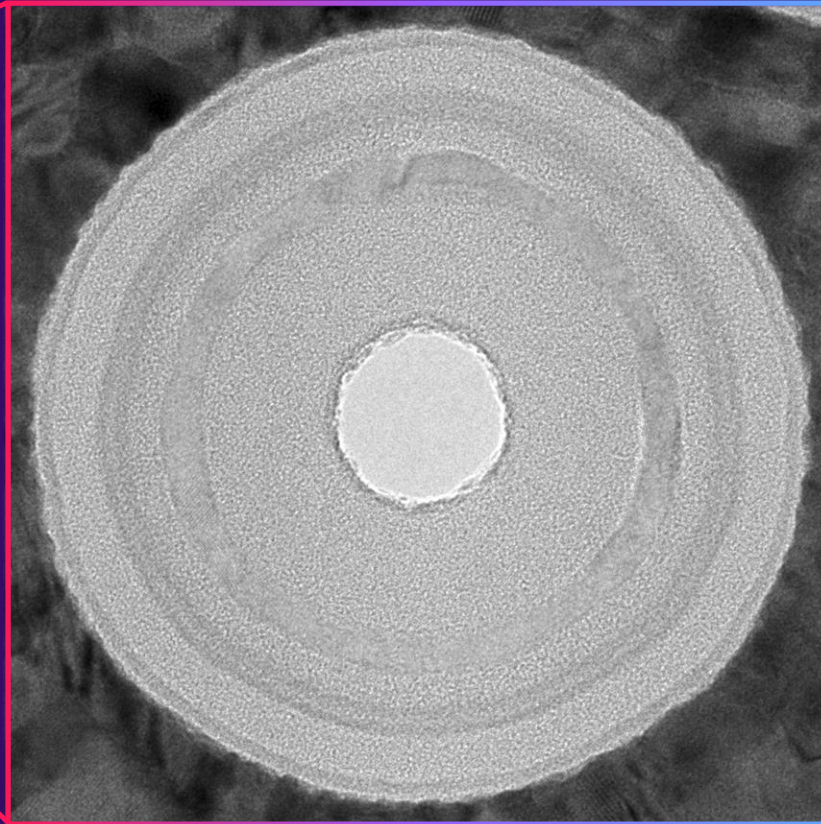


PLC



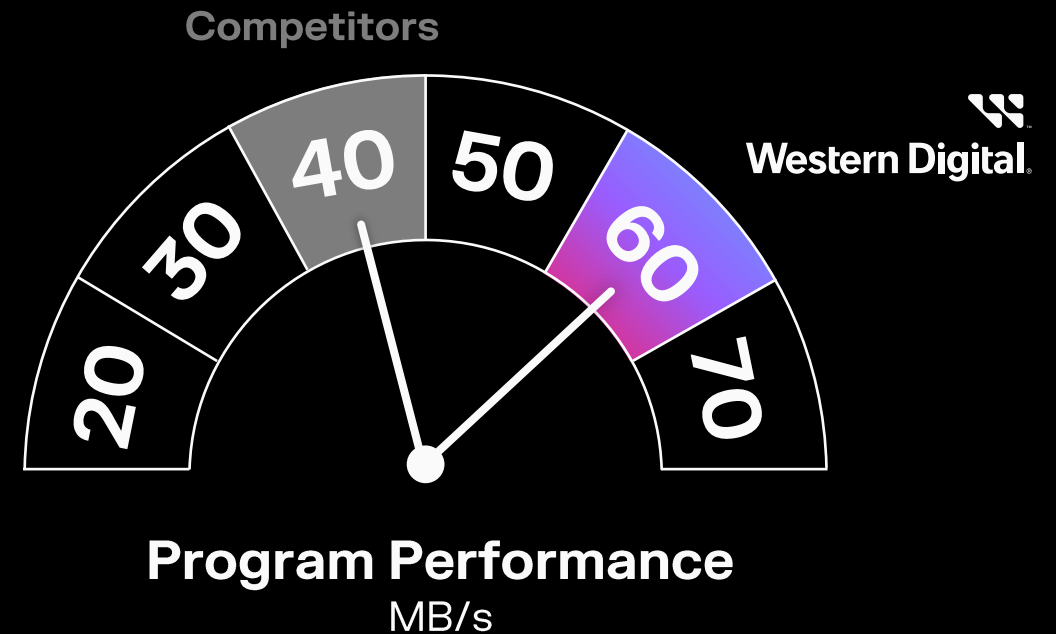
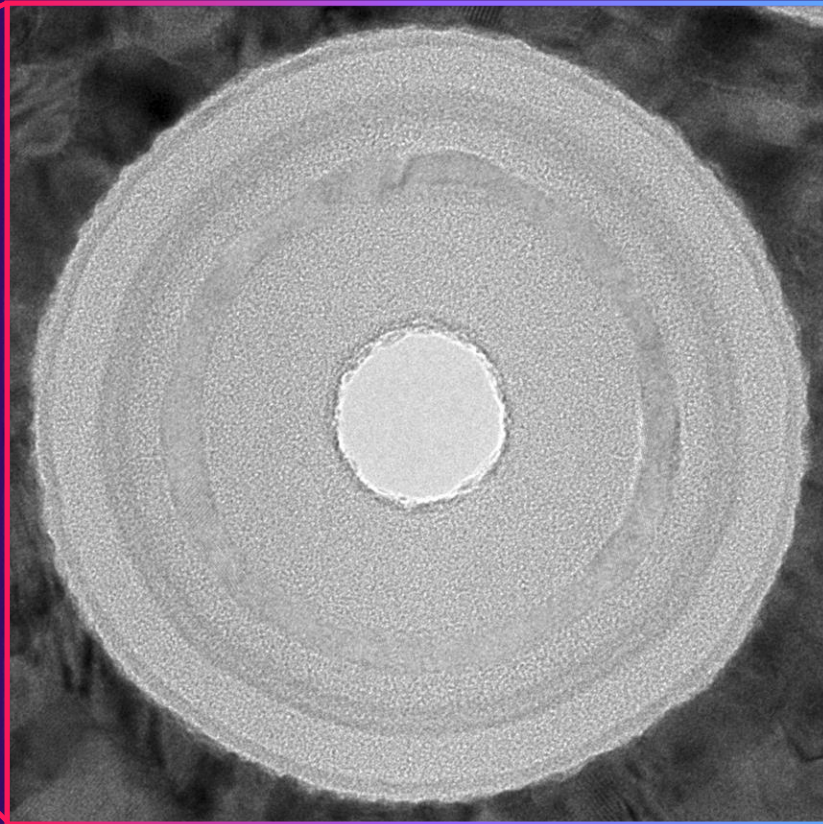
# World's Best Charge Trap Cell

Top View



# World's Best Charge Trap Cell

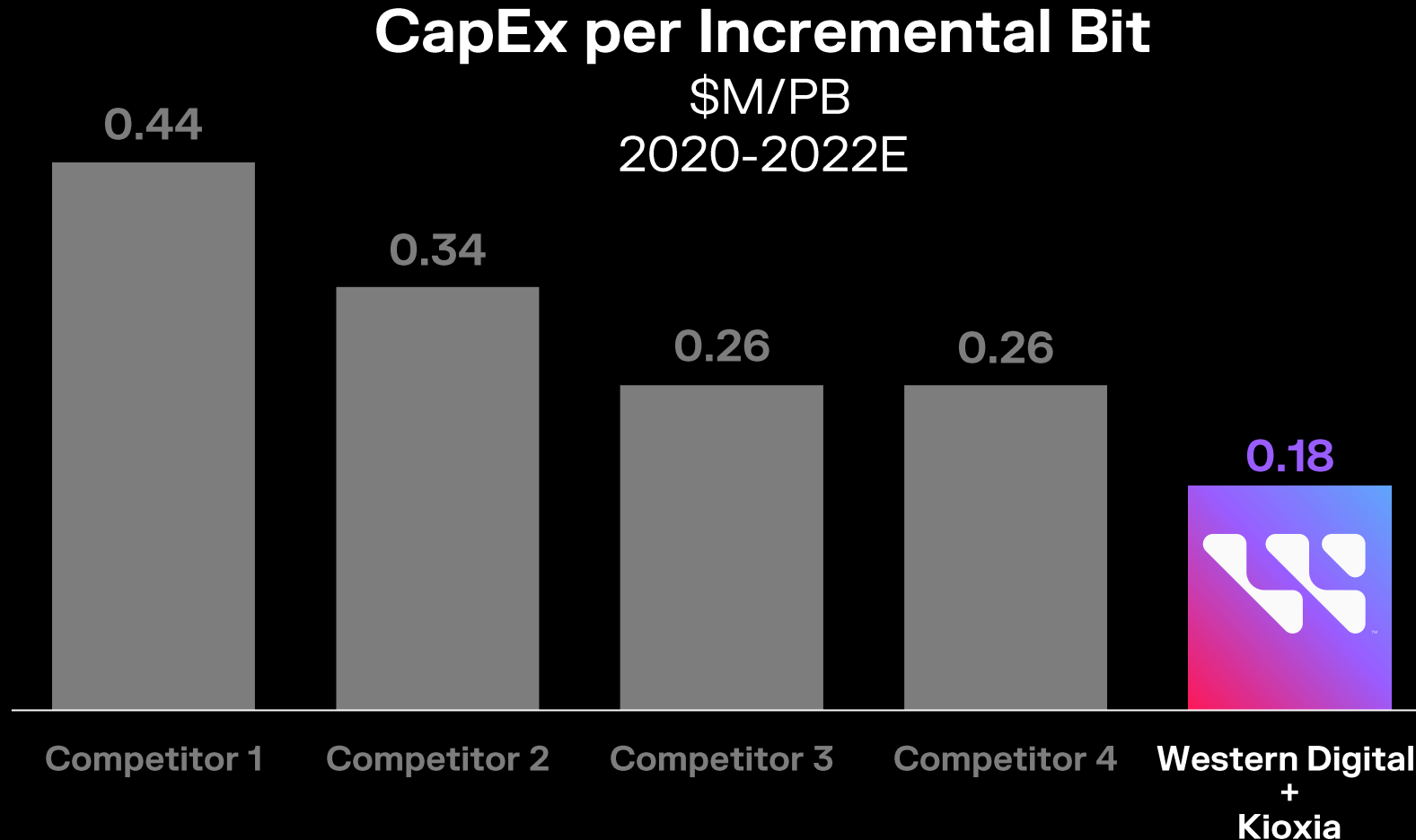
Top View



# Increasing NAND Industry Capital Intensity

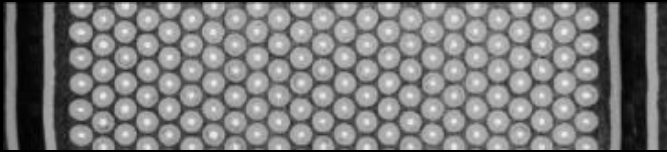


# Industry's Best Capital Efficiency

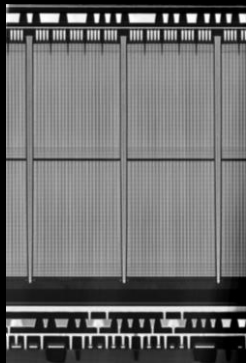


# Focus on Bit Density Leadership

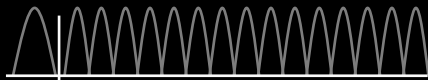
## Lateral Scaling




## Vertical Scaling (VS)



## Logical Scaling



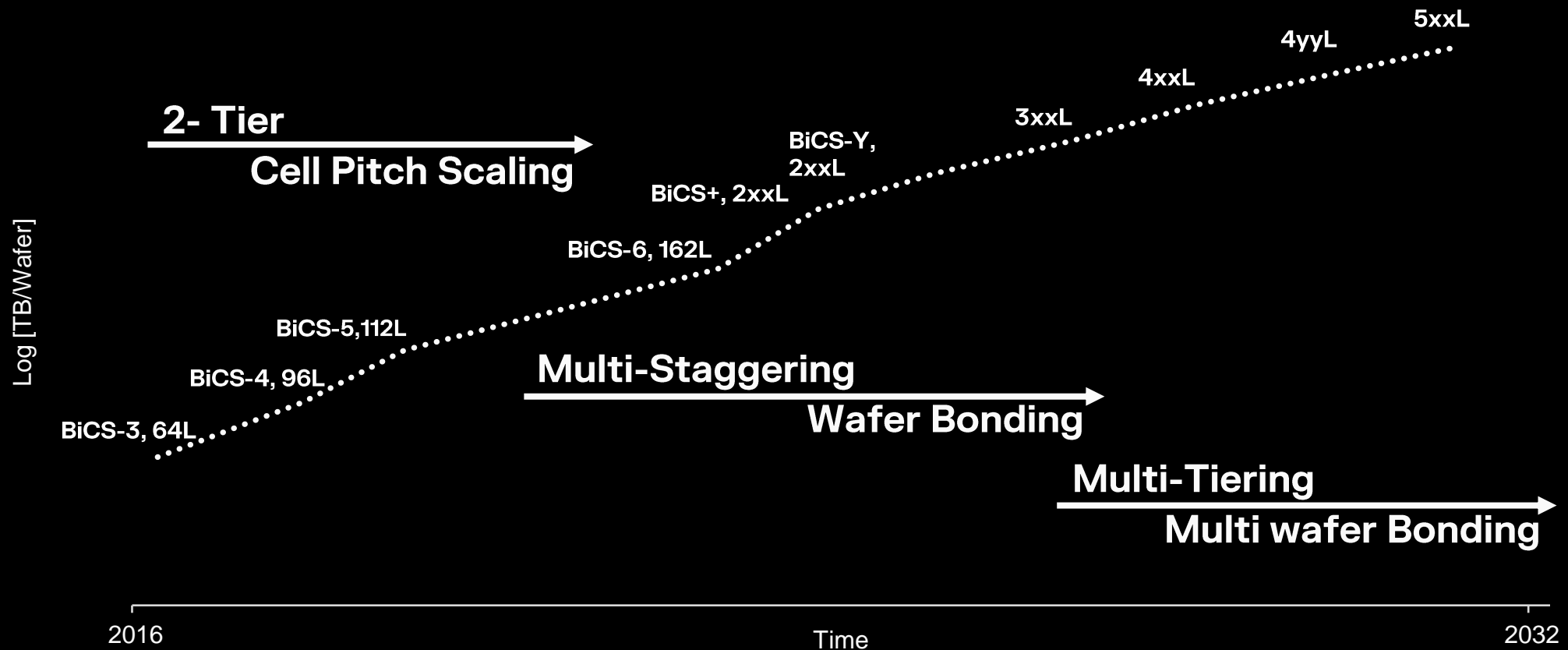
Metric	Western Digital 	Competitor 1	Competitor 2
Layer	<b>162L</b>	176L	176L
Die Size (mm <sup>2</sup> )	<b>68</b>	69.6*	69.3

\* Calculated from published bit density data

Die Capacity: 1Tb X4

Single Wafer Capacity : 100 TB

# Flash Memory Technology Roadmap



# 04

**BiCS+**

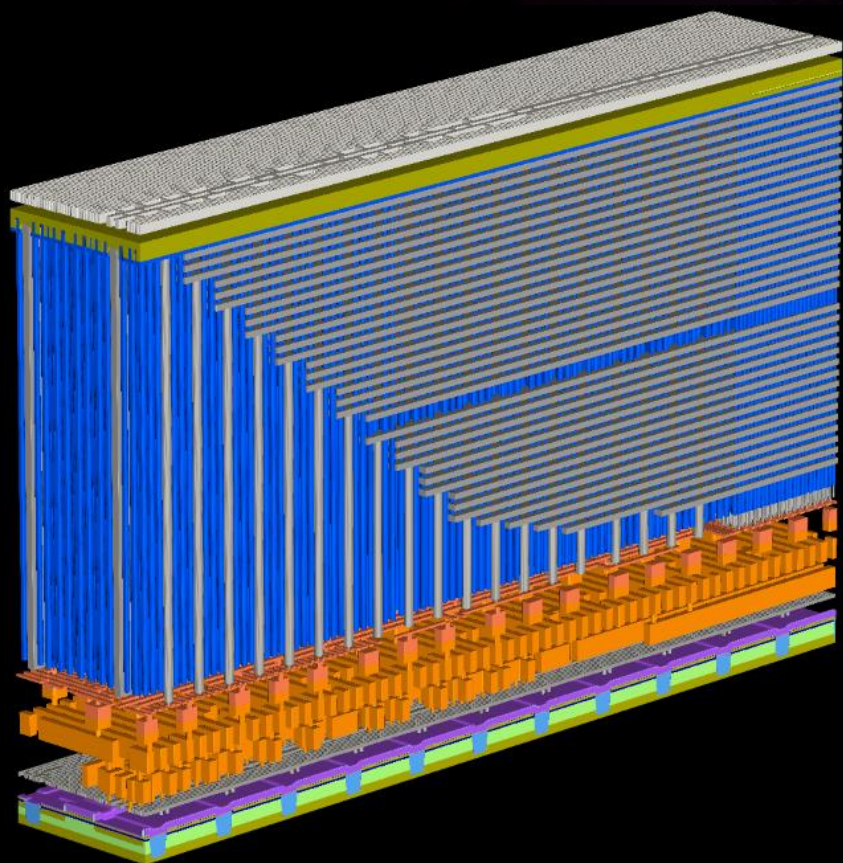


What's Next  
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Digital.**



# BiCS+

## Engineered for Datacenter Workloads



↑ **+55%**

**Bit Growth Per Wafer**  
COMPARED BiCS6

↑ **+60%**

**Transfer Speed**  
OVER BiCS6

↑ **+15%**

**Program Bandwidth**  
OVER BiCS6

# Key Takeaways

## #1 HDD

Leader in Areal Density with  
First 22TB CMR Drive Shipments  
& 26TB UltraSMR Drive Sampling

## #1 Flash

Industry Leading  
Roadmap with the  
Best Capital Efficiency

Revolutionary Data Center  
Products on the Horizon



# Western Digital<sup>®</sup>

## Create What's Next

WESTERN DIGITAL, THE WESTERN DIGITAL DESIGN, THE WESTERN DIGITAL LOGO, SANDISK, THE SANDISK DESIGN, THE SANDISK LOGO, SANDISK PROFESSIONAL, THE SANDISK PROFESSIONAL LOGO, WD, THE WD LOGO, MY PASSPORT, OPENFLEX, OPTINAND, PRO-BLADE, RAPIDFLEX, ULTRASTAR AND WD\_BLACK ARE REGISTERED TRADEMARKS OR TRADEMARKS OF WESTERN DIGITAL CORPORATION OR ITS AFFILIATES IN THE US AND/OR OTHER COUNTRIES. THE NVME AND NVME-OF WORD MARKS ARE TRADEMARKS OF NVM EXPRESS, INC. PCIE<sup>®</sup> IS A REGISTERED TRADEMARK AND/OR SERVICE MARK OF PCI-SIG IN THE UNITED STATES AND/OR OTHER COUNTRIES. ALL OTHER MARKS ARE THE PROPERTY OF THEIR RESPECTIVE OWNERS. PRODUCT SPECIFICATIONS SUBJECT TO CHANGE WITHOUT NOTICE. PICTURES SHOWN MAY VARY FROM ACTUAL PRODUCTS. NOT ALL PRODUCTS WILL BE AVAILABLE IN ALL REGIONS OF THE WORLD. 1GB = 1 BILLION BYTES AND 1TB = 1 TRILLION BYTES. ACTUAL USER CAPACITY MAY BE LESS DUE TO OPERATING ENVIRONMENT. 1 MB/S = 1 MILLION BYTES PER SECOND. READ AND WRITE SPEEDS ARE BASED ON INTERNAL TESTING; PERFORMANCE MAY VARY DEPENDING UPON HOST DEVICE, USAGE CONDITIONS, DRIVE CAPACITY, AND OTHER FACTORS.